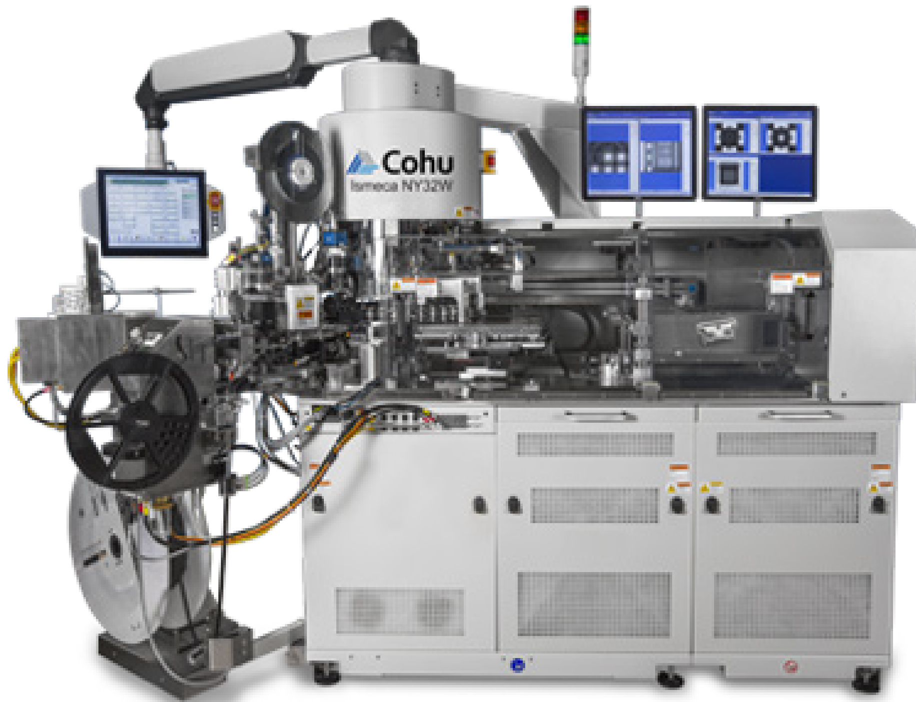
NY32W

Flexible Test and Scan Solution for FFC Devices



Automotive

Mobility

IoT/IoV & Optoelectronics

Computing & Network

Industrial & Medical

Consumer

Productivity

- Up to 30,000 UPH
- Complete Finishing Solution
  - Full Vision inspection
  - Test Contacting
  - KGD Automotive bare die testing
- Full Device Traceability

Flexibility

- Up to 12" Wafer Input
- 180° Flip-Chip under Turret
- 6 Sides inspection
- Tape and Reel Output
- Wide applicable device range 0.3 x 0.6 mm to 12 x 12 mm
  - Bare Die, Bumped Die
  - QFN/DFN
  - LED
  - MEMS

- **32-position Turret Test and Scan**
- **Down to 70 µm thin die handling**
- **KGD Automotive bare die testing**
- **Comprehensive Cohu *NV*core Inspection Solution**
  - **3D Flex® for True Ball/Bump co-planarity**
  - **Full 6 Sides inspection**

Cohu

NY32W

Flexible Test and Scan Solution for FFC Devices

Specifications

Platform

Wafer Input Media
- Film frame carrier: 4" to 12"
- Round and rectangular / plastic and metal frame
- Wafer cassette: 25 x 8", 13 x 12"

Device Range
- WLP: 0.3 x 0.6 to 12 x 12 mm / thickness ≥0.07 mm
- QFN: 0.3 x 0.6 to 12 x 12 mm / thickness ≥0.30 mm
- LED: 0.5 x 0.5 to 6 x 6 mm / thickness ≥0.10 mm

Index Time
- Down to 80 ms, depending on device and process

Performance Characteristics
- WLP: up to 24,000 UPH
- QFN: up to 30,000 UPH
- LED: up to 30,000 UPH
- With Wafer output: up to 20,000 UPH
- MTBA: typ. >2 h
- MTBF: typ. >168 h
- Conversion time: typ. <45 min

Interface
- TTL parallel interface for Tester and Laser
- RS232, GPIB (optional)
- Network: Ethernet capability
- Wafer Mapping: SECS GEM
- (SEMI E4, 5, 30, 37 SEMIG84)

ESD
- According to ANSI / ESD SP10.1
- ESD Class 0 (optional)

Facility Requirements
- 100 VAC - 240 VAC 50/60 Hz, One Phase
- 2 kVA / 3.5 kVA with vacuum pump (optional)
- Air Pressure range: 5-10 bar ± 0.5 bar
- Air consumption: 5 m^3/hour (typical)
- Vacuum Network: -0.5 Bars ± 10%
- Consumption: typ. 420 l/min (typical)

Dimensions
- Overall dimension: 2.3 x 2.0 x 2.1 m
- Floor space requirement: 3.0 x 2.3 x 2.1 m
- Weight: net typ. 1200 kg / gross typ. 1700 kg
- With Wafer output configuration:
  - Overall dimension: 2.8 x 1.2 x 2.1 m
  - Floor space requirement: 3.5 x 1.5 x 2.1 m
  - Weight: net typ. 1500 kg / gross yp. 2000 kg

Standards
- CE
- S2/S8 assessment
- 2006/42/EC Machinery
- 2004/108/EC Electromagnetic compatibility (EMC)
- 2006/95/EC Low Voltage

Process Capabilities

Input
- Wafer, De-taping, Bowl, Tube

Output
- Tape & Reel, Tube, Tray
- Wafer output, LED 64 Bulk Sorting

Processes
- Device Flip
- X-Y-T touchless precisor
- Test Contacting
- Electrical Tester (Discrete)
- LED optical test (ambient & temperature 85˚C)
- Laser marking
- 6 Sides Vision inspection
- Bulk, Tube, Tray Sorting
- Waffle PAK, Wafer Sorting
- Dual Tape & Reel with flip-flop
- Automatic rejection & replacement in-tape
- Auto Reel Changer
- Wafer map with full device traceability

*NV*core Vision Inspection
- 1D/2DMC code reader, ViewMap®
- 2D/3D Flex® ball/bump co-planarity
- Mark, Surface, 5S, Color Vision
- In-Tape, Post Sealing inspection
- LED dedicated solutions

Contactor
- Cohu offers contact sockets for all package versions and applications, i.e. One Touch Socket "High Amps", Flat Test Kelvin, Small Device Kelvin, Pogo pin pocket, LED dedicated solutions

Specifications subject to change without notice.
For detailed performance specifications, please contact Cohu.

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www.cohu.com/ny32w
www.cohu.com/test-handlers

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